

Issue Date:30 Mar 2021

Title of Change:	Update to FPCN23609X: Removal of products listed in the original FPCN "Second source site addition for final test and shipping tray change for AR0330 CSP products."			
Proposed First Ship date:	23 Apr 2021 or earlier if approved by customer			
Contact Information:	Contact your local ON	emiconductor Sales Office or Geethakrishnan.Narasimhan@onsemi.com		
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <pcn.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.</pcn.samples@onsemi.com>			
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Amy.Wu@onsemi.com			
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com			
Marking of Parts/ Traceability of Change:	Date Code Apr 2021			
Change Category:	Test Change, Assembly Change			
Change Sub-Category(s):	Manufacturing Site Addition			
Sites Affected:				
ON Semiconductor Sites		External Foundry/Subcon Sites		
None		Huatian Technology, China		
		KYEC, Taiwan		
		Xintec (ISBU)		

Description and Purpose:

This is an update to the original FPCN23609X. Products listed in this update are not impacted by the change described below.

This final product change notification (FPCN23609X) communicates the addition of KYEC as a final test site and the conversion of the tray used for shipping from a 2inch tray to a 4inch tray. The table below summarizes the changes. The addition of test site at KYEC (Taiwan) is being done to add capacity to our current test site at Huatian (HTKS). There is no change in test program, test limits or control plan. The proposed tester platform in KYEC is already in production for other image sensor products for more than 7 years.

Backend Manufacturing	Before Change Description	After Change Description
Final Test Site (FT)	-Huatian (HTKS)	-Huatian (HTKS) -KYEC
Shipping Tray Manufacturer and Size	Yanginic Tray, 2inch	Hung Yang, 4inch
Tester Platform	DoThinKey at HTKS	-DoThinKey at HTKS -IP750EX at KYEC
Tester Handler	Homegrown at HTKS	-Homegrown at HTKS -HT9045 at KYEC

There is no product marking change as a result of this change. The difference in appearance of the tray is shown below.

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Final Product/Process Change Notification

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Test	HBin	SBin	Parts	Pass Yield		
PASS	1	1	973	100%		
FAIL UNITS			158			
Test	HBin	SBin	Parts	Fail Yield		
Shorts_Test	8	49**	25	100%		
Leakage	8	45**	5			
Continuity	8	48**	7			
ADC	5	51**	65			
MidL	5	57**	20			
Dark	5	56**	36			
List of Affected Pa Note: Only the stand specific PCN addend	dard (off the shelf)			t. Any custom parts affected by this PCN are shown in the customer red Portal.		
Part Number				Qualification Vehicle		
AR0330CM1C00SHKA0-CP				AR0330CM1C21SHKA0-CP		

AR0330CM1C00SHKA0-CP	AR0330CM1C21SHKA0-CP		
AR0330CM1C12SHKA0-CP	AR0330CM1C21SHKA0-CP		
AR0330CM1C12SHKA0-CR	AR0330CM1C21SHKA0-CP		
AR0330SR1C00SUKA0-CR	AR0330CM1C21SHKA0-CP		
AR0330SR1C00SUKA0-CP	AR0330CM1C21SHKA0-CP		
AR0330CS1C12SPKA0-CR	AR0330CM1C21SHKA0-CP		
AR0330CS1C12SPKA0-CP2	AR0330CM1C21SHKA0-CP		
AR0330CS1C12SPKA0-CP	AR0330CM1C21SHKA0-CP		



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
AR0330CS1C12SPKA0-CR		AR0330CM1C21SHKA0-CP	NA	
AR0330CS1C12SPKA0-CP2		AR0330CM1C21SHKA0-CP	NA	